



Discrete Carbon Nanotubes vs. Carbon Fiber: Nano-Uniform Surface Resistance for Next Gen ESD-Safe Fixtures

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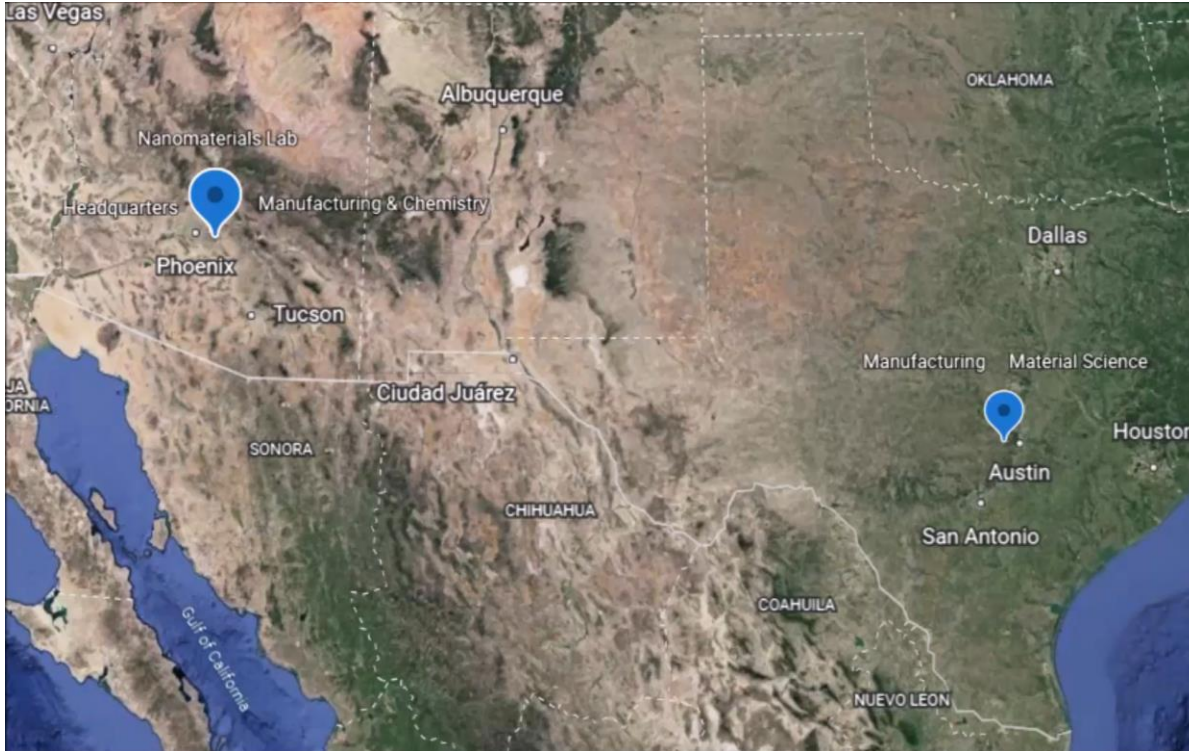


Presentation Outline

- Elect Nano Company Introduction
- Core Technology and Capabilities
- Discrete CNTs for Injection Molding
 - Dispersion of CNTs Thermoplastics
 - Use case for JEDEC trays
 - Electrical Property Testing
 - Laser Marking

*Create Exceptional Value Together
As We
Nano-Engineer Electronic Materials*

Accomplishments & Readiness



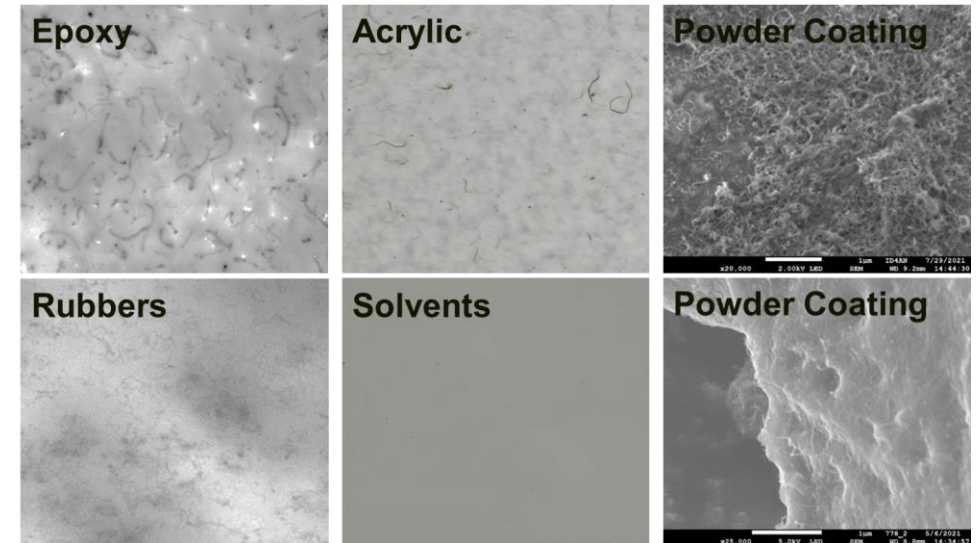
- ⬡ Largest Functionalized CNT manufacturing facility in the world
- ⬡ Captive manufacturing of masterbatches and final products
- ⬡ Augmented with contract and toll manufacturing

120 Patents including dCNT 'composition of matter' patents

World's ONLY discrete, functionalized, dispersed Carbon Nanotubes (dCNTs)

World's first to:

- ⬡ Ink jet CNTs (Polyjet systems)
- ⬡ Add electrical conductivity into AM Resins
- ⬡ Powder Coated CNTs
- ⬡ Improve binding with CNTs
- ⬡ Increase Impact with CNTs
- ⬡ Much more.....



Protected & Proven

PROTECTED

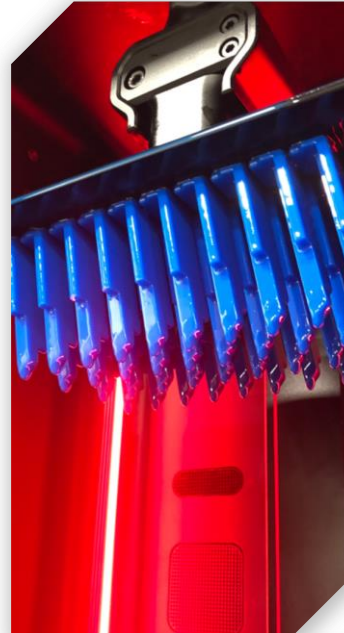
120+ Patents

Composition of Matter Patents

Secure Knowledge Library

Proprietary Functionalization
and Dispersion Technology

PROVEN



mechnano

Additive
Manufacturing



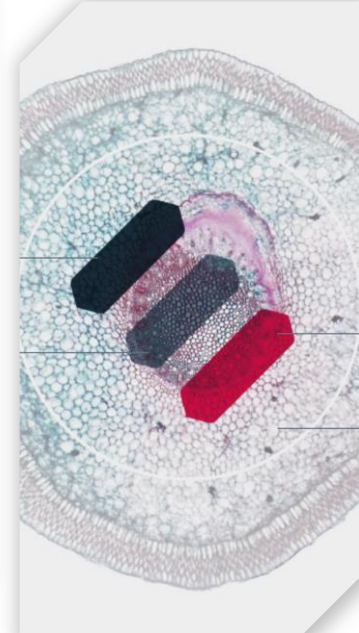
**BLACK DIAMOND
STRUCTURES™**

Energy
Storage



MRD

Engineered
Rubber



biopact

Medical
Treatment

Executive Team

CEO

CLO/CFO

Director Business
Development

CTO



Steve Lowder

Scott Gillette

J.D, C.P.A., LL.M.

David Torp

PE

Brandon Sweeney

Ph.D.



cadence®



ARL



“Next Revolution in Material Science” – Discovered in 1991

- ◇ Diameter is 10,000× smaller compared to a human hair
- ◇ Compared to steel
 - ◇ 100× higher tensile strength (no fatigue failures)
 - ◇ 100× higher thermal conductivity
 - ◇ 6× lighter
 - ◇ 5× higher modulus
- ◇ Compared to copper
 - ◇ 5× electrical conductivity
 - ◇ 15× thermal conductivity
 - ◇ 1,000× current capacity

3 Fundamental Challenges

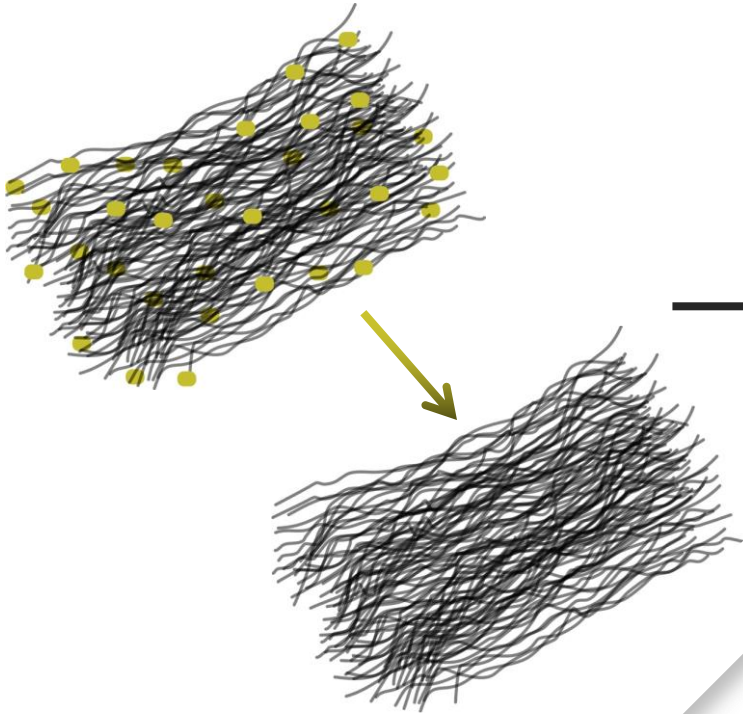
CNTs clump together during manufacturing into bundles that are extremely difficult to untangle.

CNTs are exceptionally challenging to disperse uniformly.

CNTs are hard to keep apart.

3 Key Steps

1



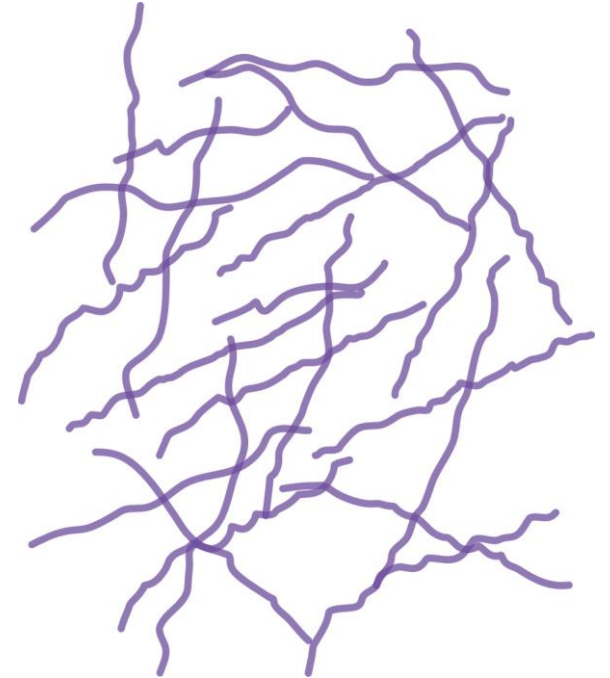
CLEAN

2



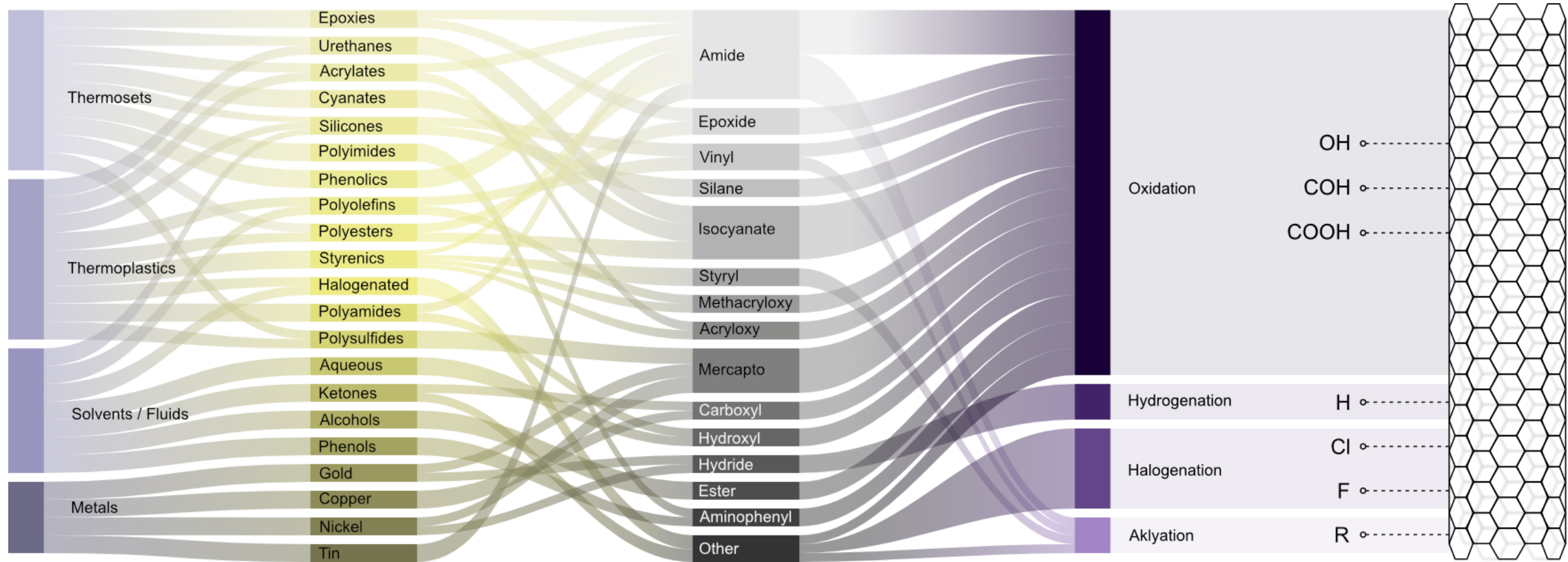
DEBUNDLE

3

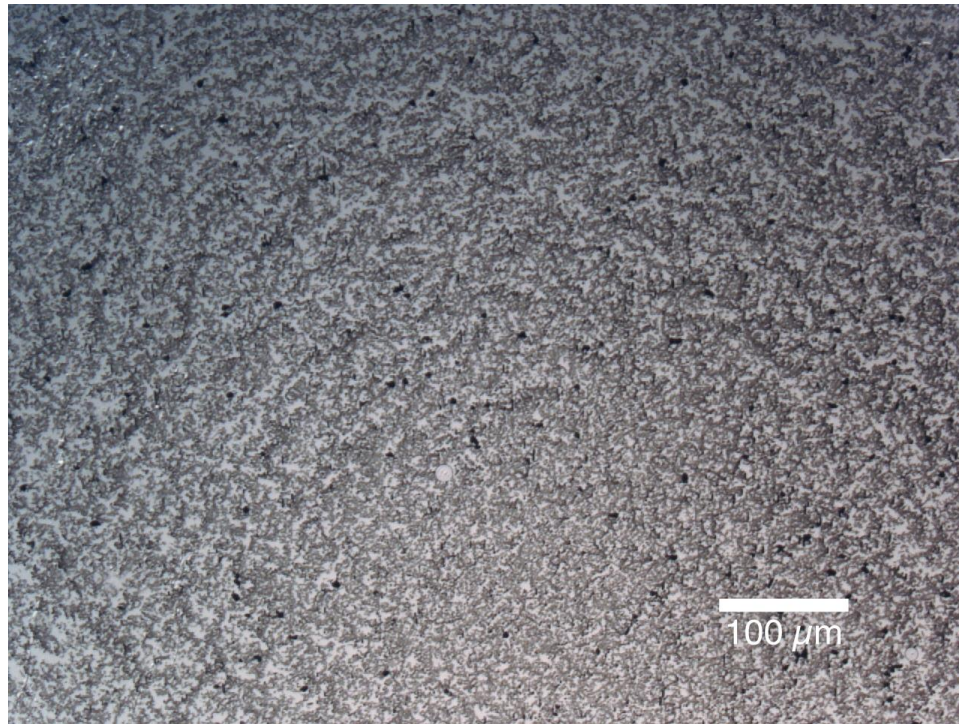


FUNCTIONALIZE

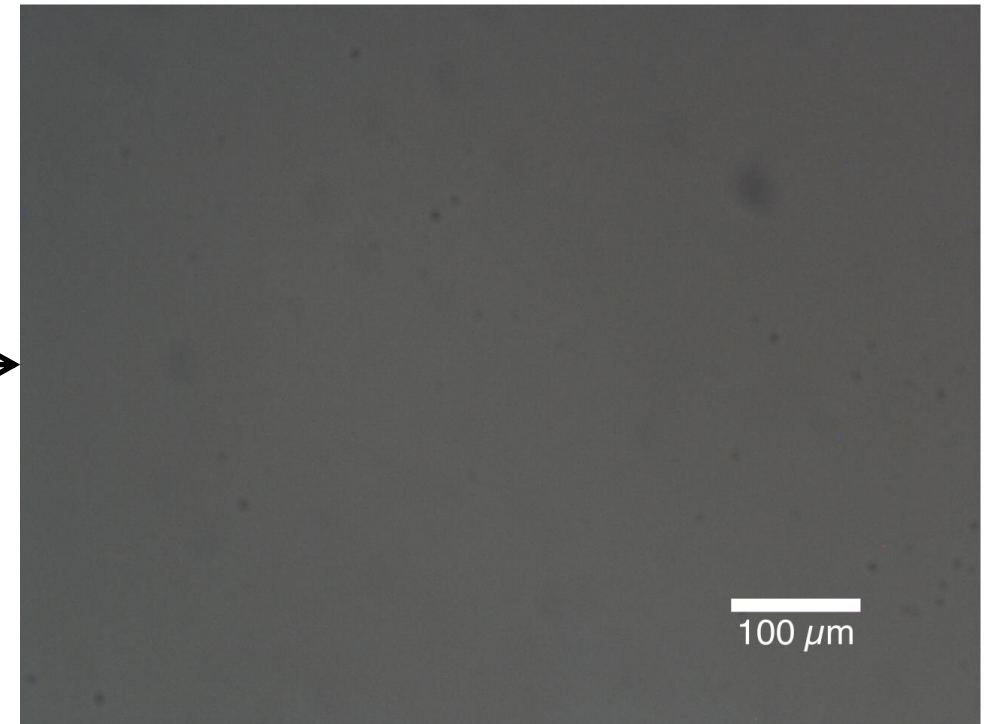
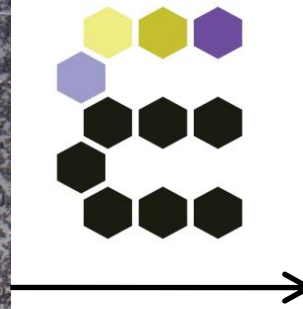
DCNTs Modification



Matching DCNTs Surface Thermodynamics



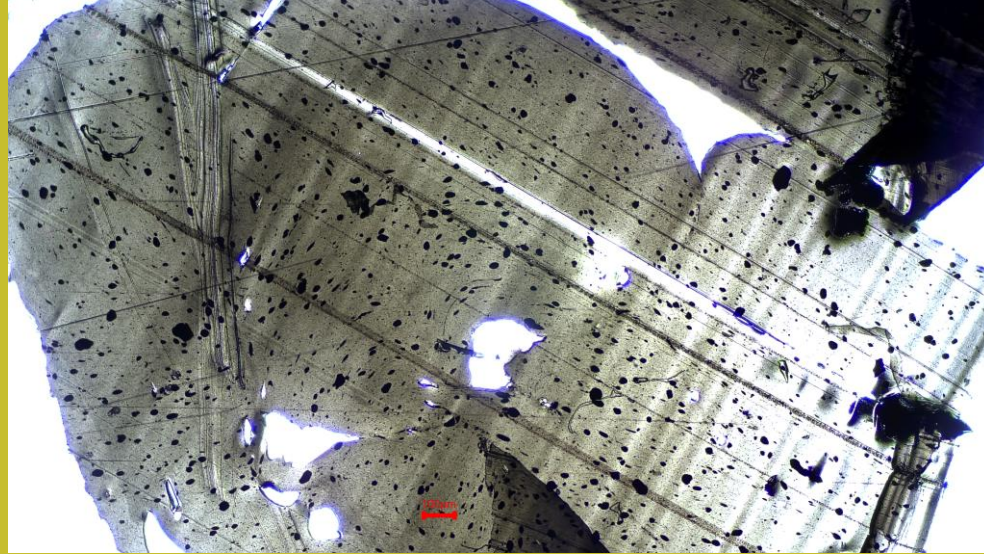
UNSTABLE DISPERSION



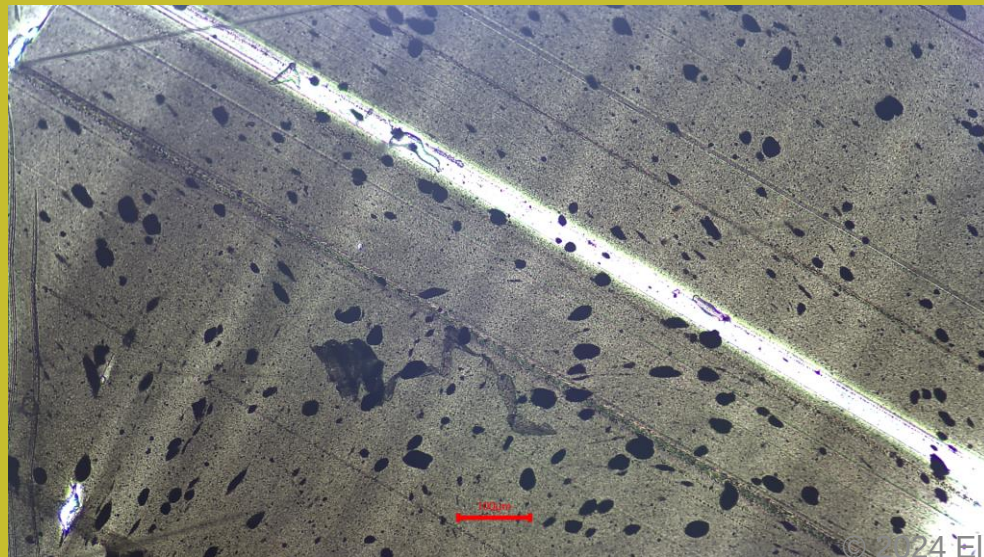
STABLE DISPERSION

CNT Dispersion | Elect Nano vs. Others

Commercial CNT MB in PETG

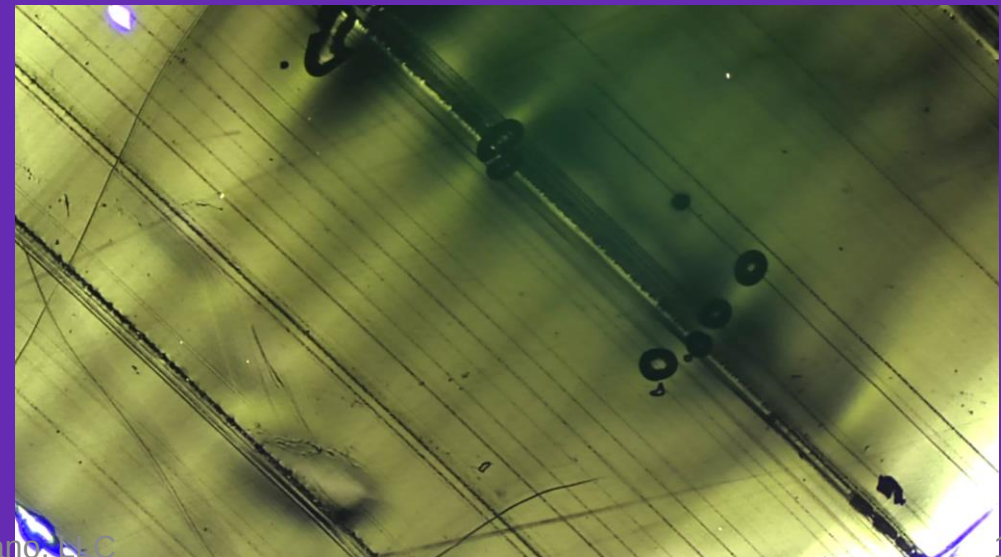
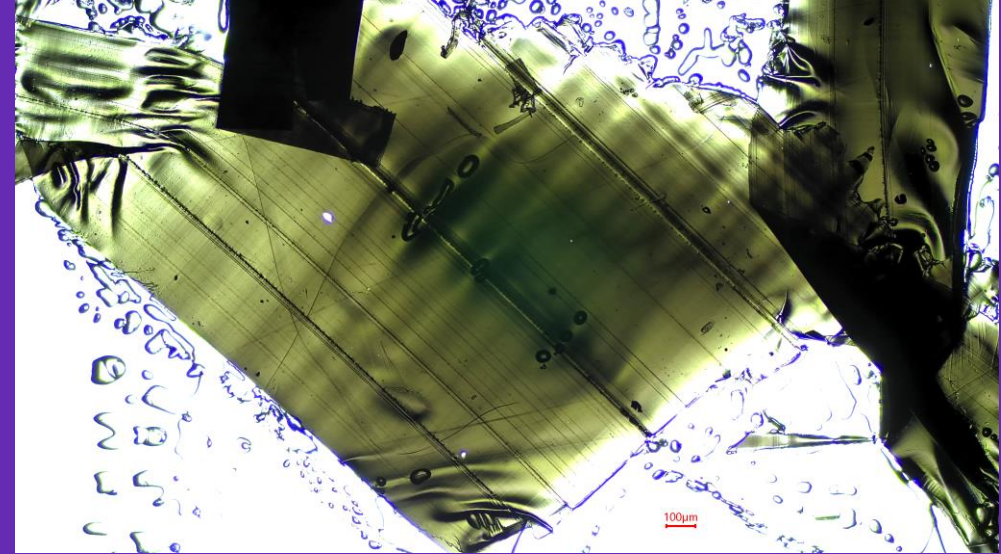


Mag = 4X

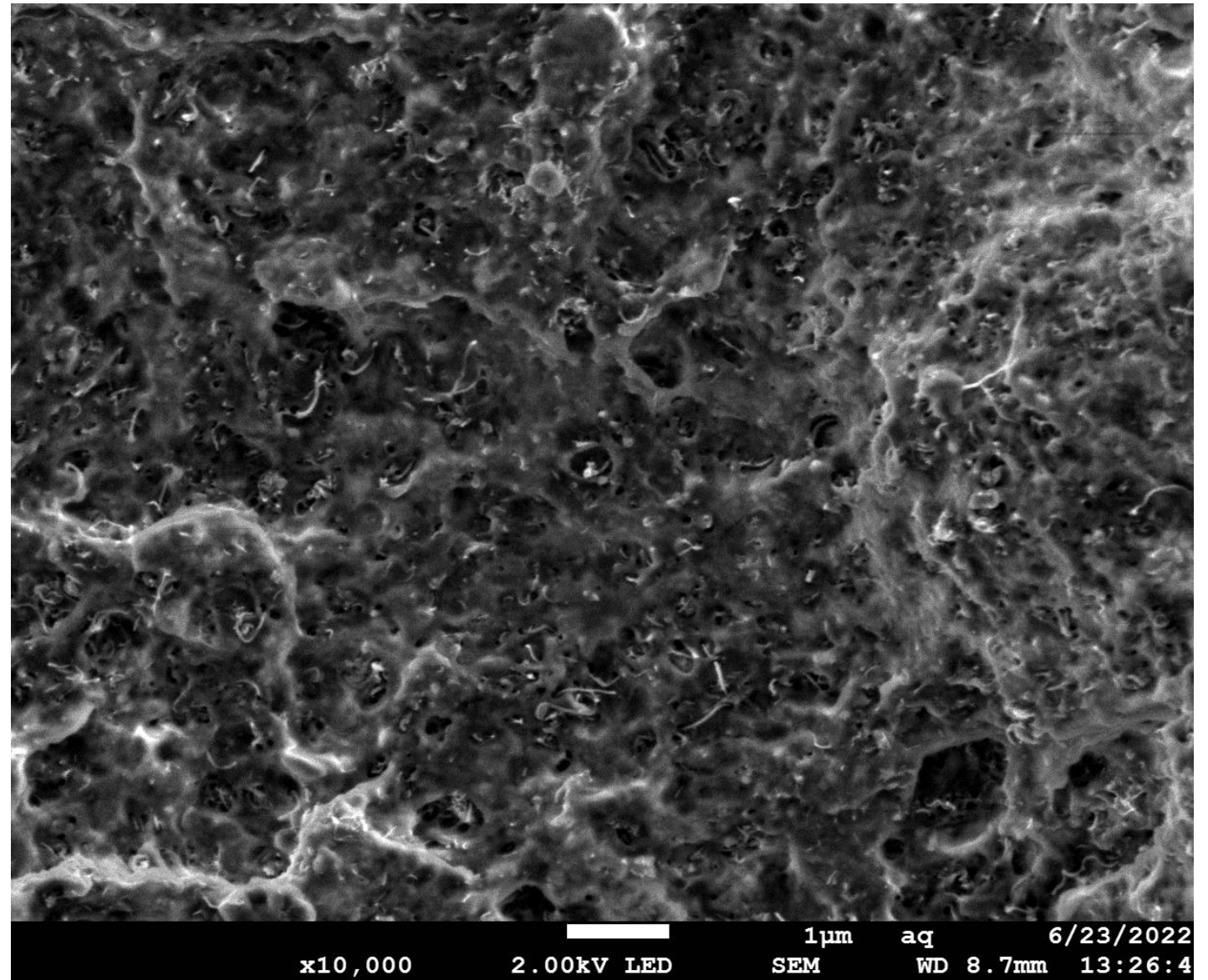
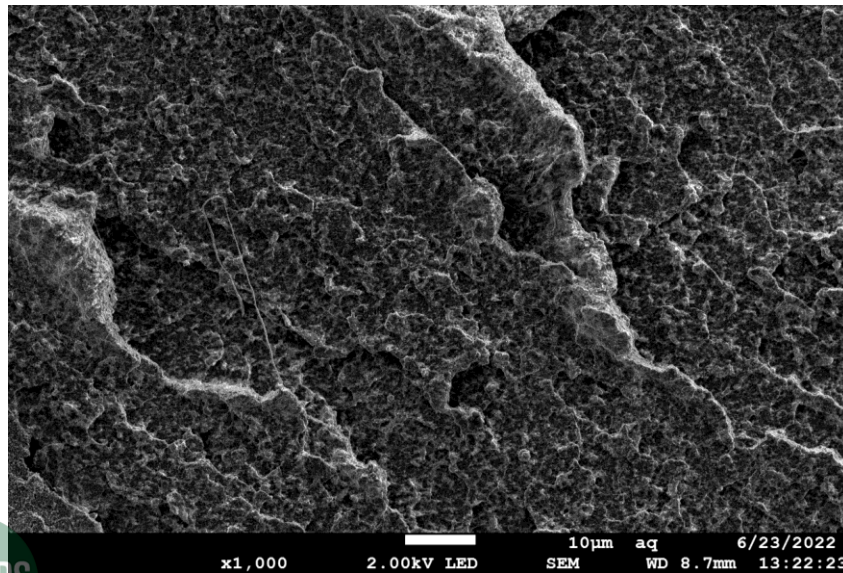
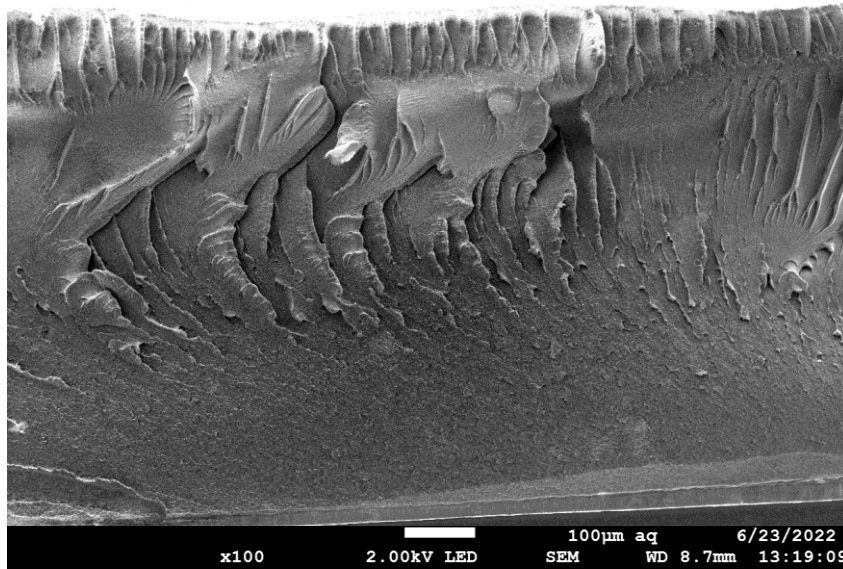


Mag = 10X

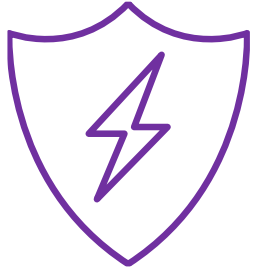
Elect Nano dCNT in mPPO



Discrete CNTs | SEM of Carbon Nanotubes in PC

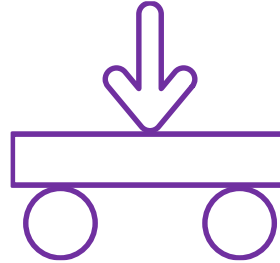


Nano-Engineering Solution



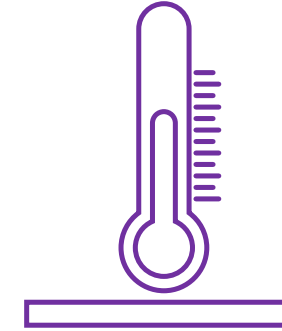
- ESD
- EMI
- Conductive
- Insulating

Electrical



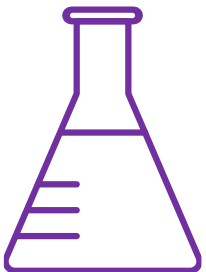
- Strength
- Impact
- Toughness
- Modulus

Mechanical



- Conductivity
- CTE
- Stability

Thermal



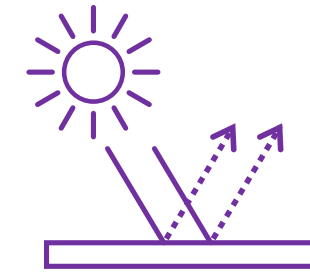
- Corrosion
- Resistance
- Reactivity

Chemical



- Diamagnetic
- Paramagnetic
- Ferromagnetic

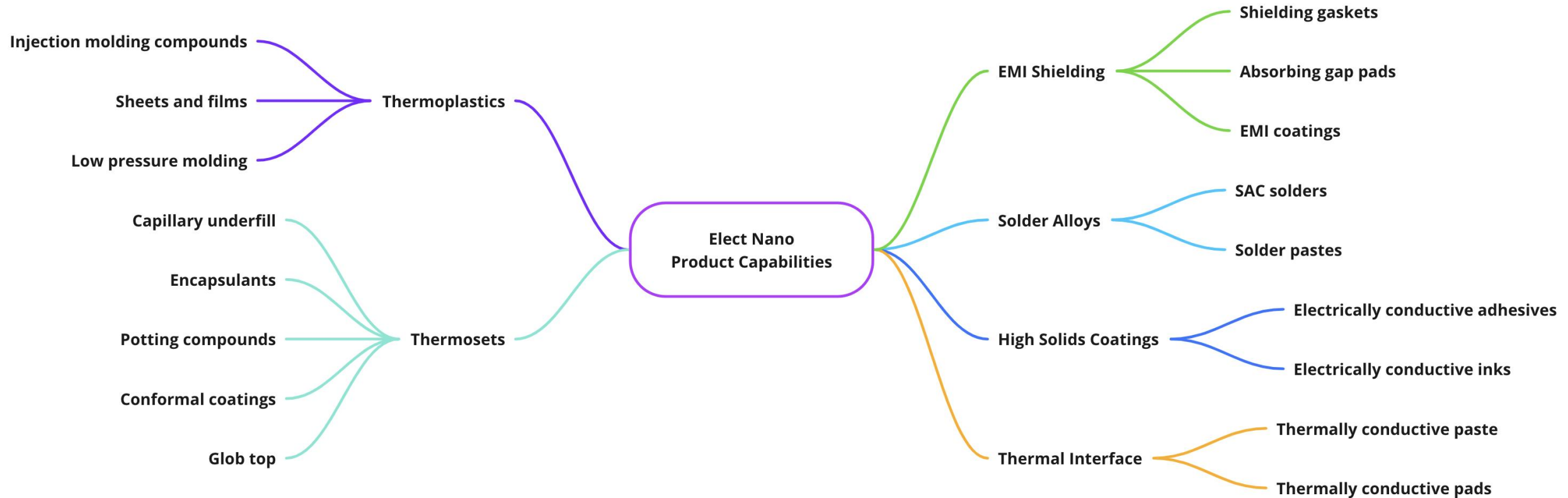
Magnetic



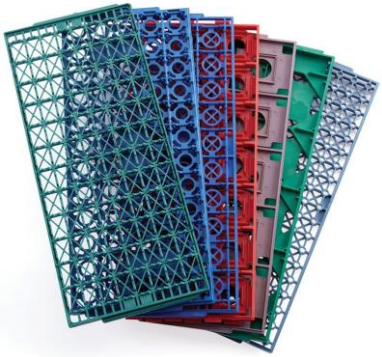
- Absorbance
- Transmittance
- UV Protection
- Anti-reflective

Optical

Product Capabilities



CNT Nanocomposite Injection Molding Compound



- Use case is for wafer media handling trays
 - JEDEC trays for wafer, die, and ICs
 - Wafer Cassettes
 - Waffle Packs
 - Matrix Tray
- Used in high volume for IC manufacturing
- High mix for new chip product with unique dimensions
- Must be ESD safe
- **Current molding compounds have shortcomings addressable by Elect Nano discrete CNT technology**

Carbon Fiber

25 μm

VS.

Discrete CNTs

100 nm

X HIGHLY VARIABLE ELECTRICAL CONDUCTIVITY

High

Orientation

Low

✓ PRECISE, TUNABLE ELECTRICAL CONDUCTIVITY

X HIGHLY VARIABLE MECHANICAL PROPERTIES (STIFFNESS)

High

Percolation

Ultra-Low

✓ UNIFORM ISOTROPIC MECHANICAL PROPERTIES (STIFFNESS)

X >10WT% REQUIRED FOR ESD

✓ <5WT% REQUIRED FOR ESD

X SHEATHING AND SLOUGHING

✓ NO SHEATHING, NO SLOUGHING

X GENERATING FPM

✓ NO FPM

X HIGHLY VARIABLE SURFACE FINISH

✓ UNIFORM SURFACE FINISH

X NON-UNIFORM GRAY VALUES (VARIABLE GRAYS)

Poor

Surface Finish

Excellent

✓ ULTRA-LOW GRAY VALUES (VERY BLACK)

X UNREADABLE LASER MARKING

✓ EXCELLENT LASER MARKING

✓ HIGH STIFFNESS AT TYPICAL LOADING LEVELS

Very High

Stiffness

Low

With Secondary Bulk Fillers

~ LOW STIFFNESS AT TYPICAL LOADING LEVELS, CAN BE IMPROVED WITH SECONDARY FILLERS

Sample Preparation

Injection Molded Dogbones



Surface Resistance | Flow Alignment Effects

CARBON FIBER



Position	Resistance (Ohms)
Top	$<1.00\text{E}+03$
Middle	$5.49\text{E}+09$
Bottom	$>1.00\text{E}+12$
Log Trans. Mean	$1.76\text{E}+08$
Log Trans. Range	$>1.00\text{E}+09$

CF



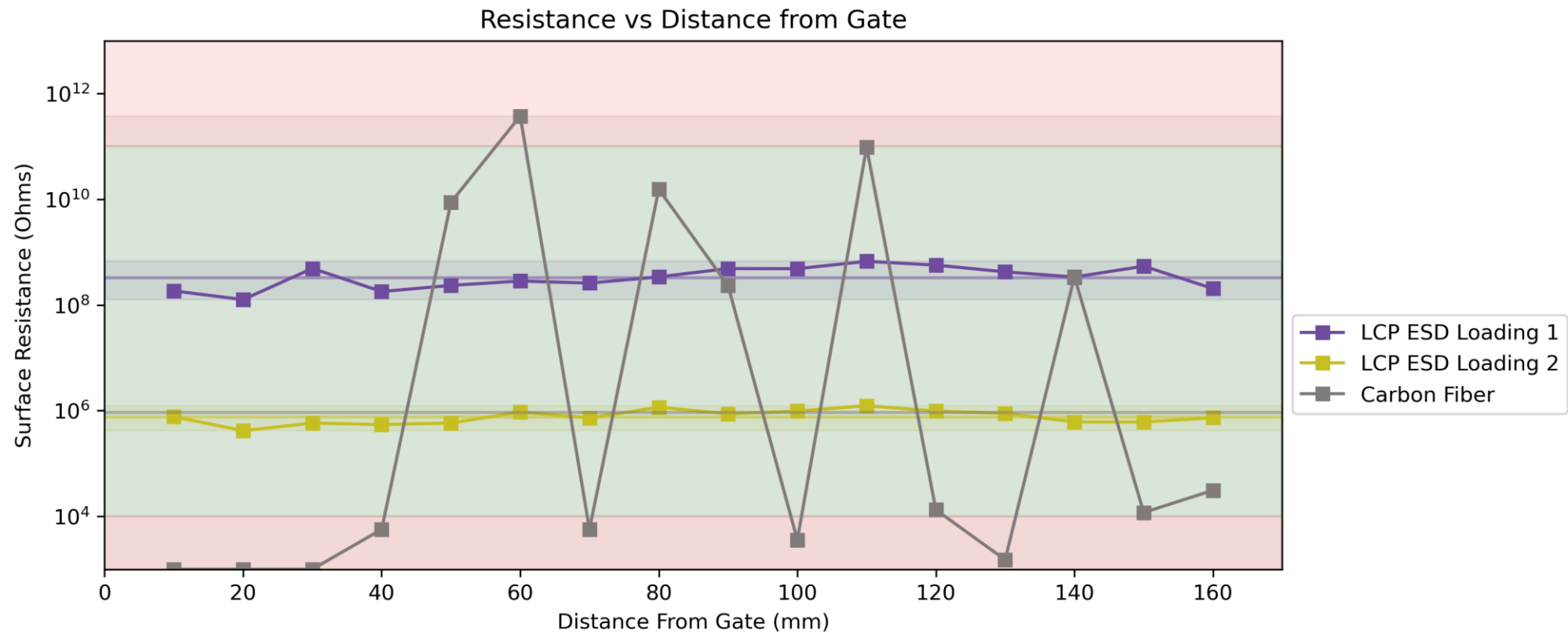
DISCRETE CNT

Position	Resistance (Ohms)
Top	$9.73\text{E}+08$
Middle	$1.12\text{E}+08$
Bottom	$2.20\text{E}+08$
Log Trans. Mean	$2.88\text{E}+08$
Log Trans. Range	$8.69\text{E}+00$

dCNT



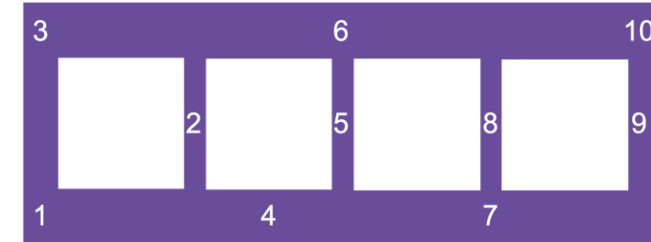
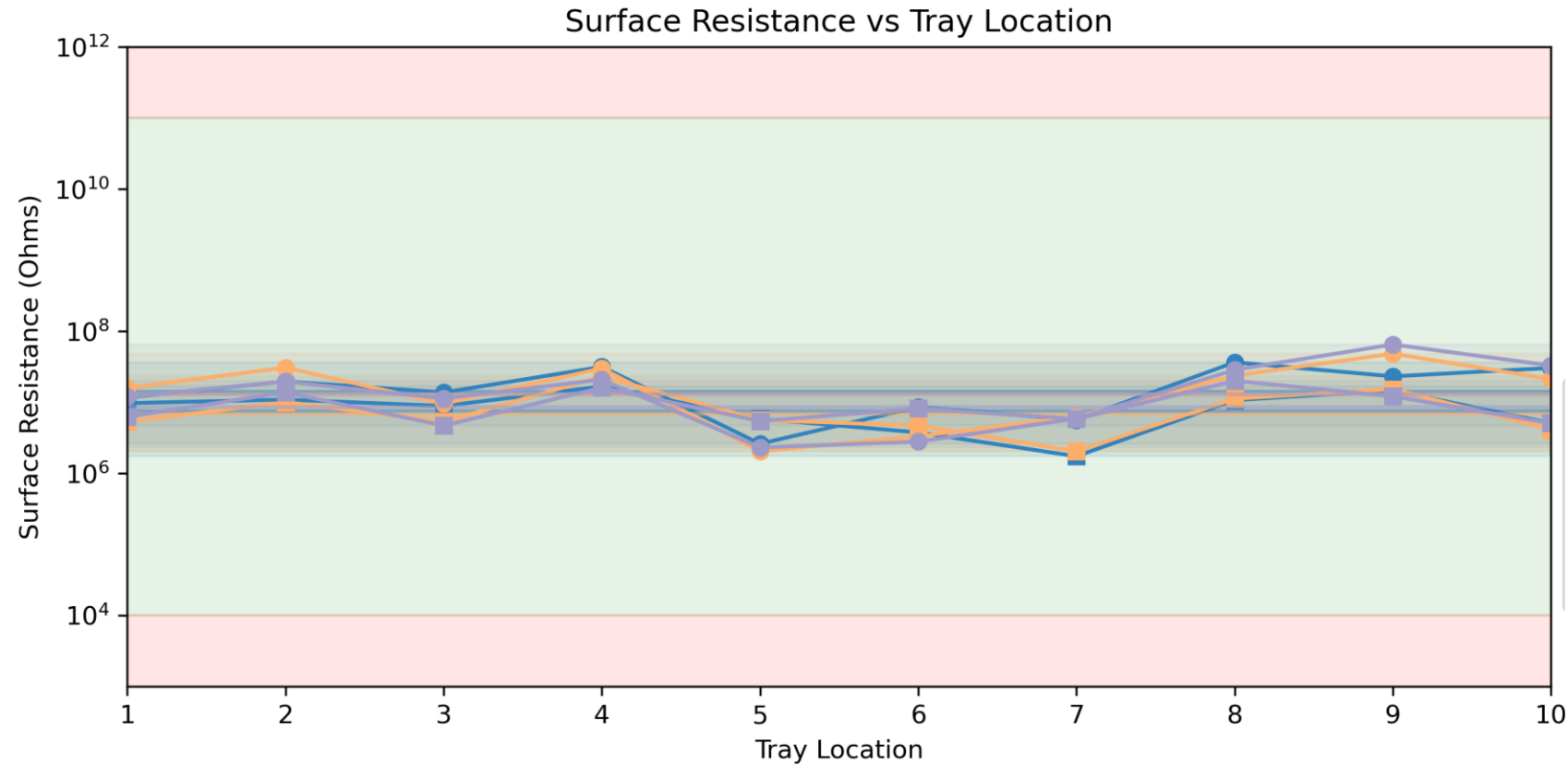
LCP GFR35 Results | Surface Resistance



Dogbone ID	Side	Log Trans Mean	Log Trans Range
LCP ESD Loading 1	Core	3.26e+08	5.30e+00
LCP ESD Loading 2	Core	7.58e+05	2.97e+00
Carbon Fiber	Core	9.32e+05	3.74e+08



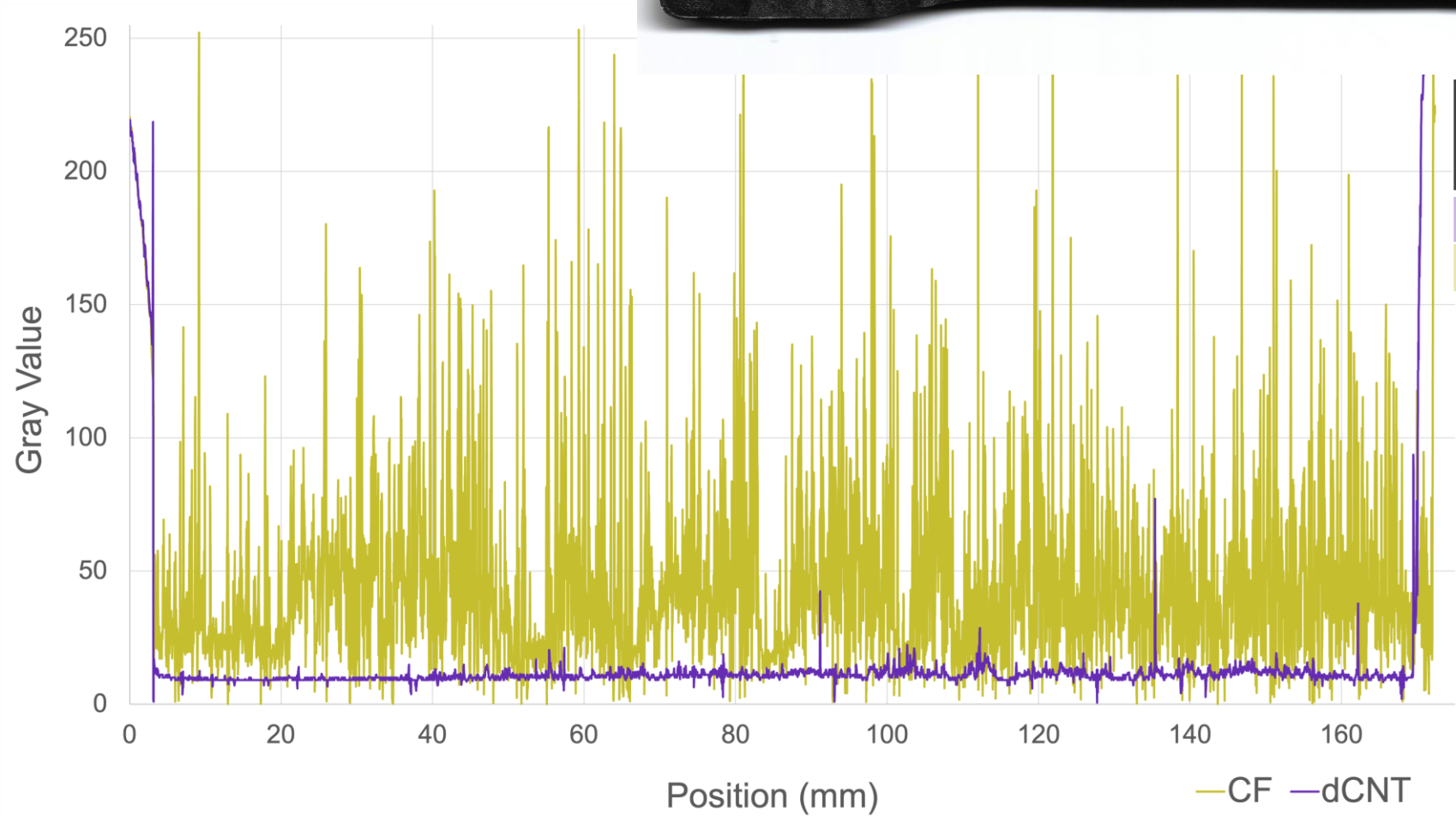
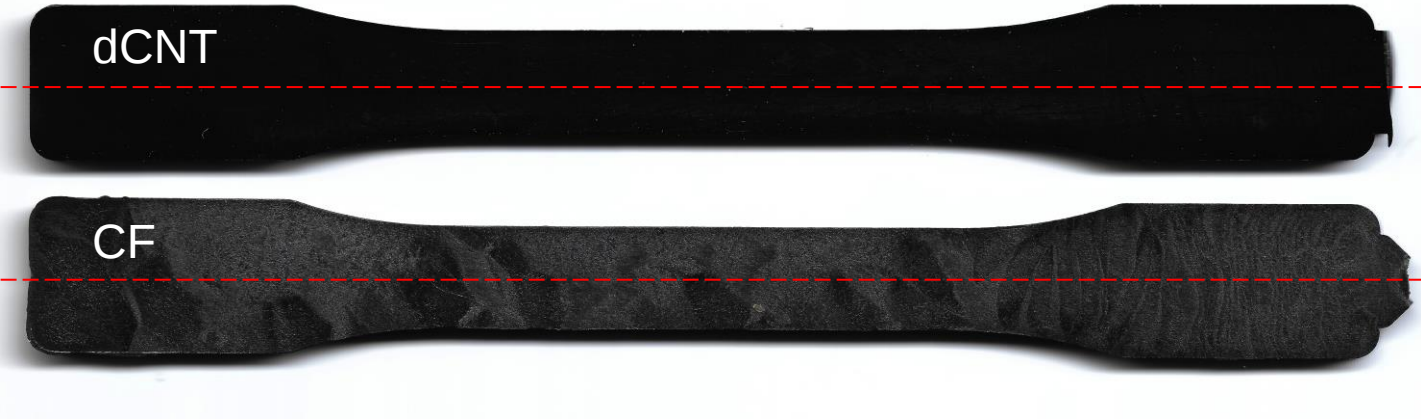
LCP GFR35 Results | Injection Molded Trays



Tray ID	Side	Log Trans Mean	Log Trans Range
10-A	Top	1.40e+07	1.40e+01
10-A	Bottom	7.30e+06	9.59e+00
10-B	Top	1.29e+07	2.37e+01
10-B	Bottom	6.85e+06	1.13e+01
10-C	Top	1.28e+07	2.81e+01
10-C	Bottom	8.45e+06	4.27e+00

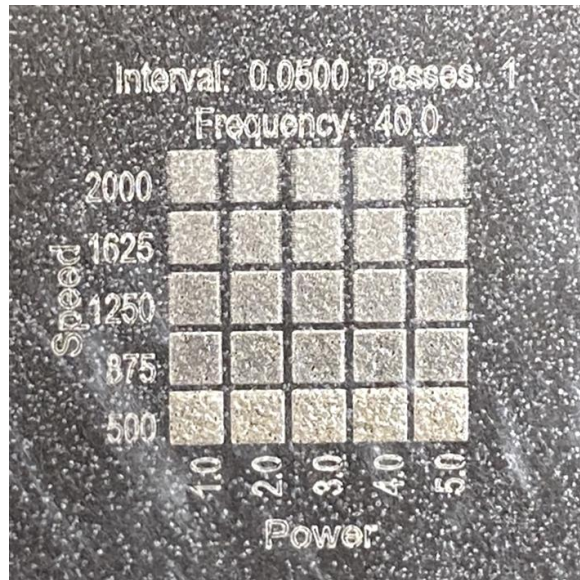
Surface Finish

Color Uniformity



Sample	Avg. Gray Value	Std. Dev.
dCNT	10.8	2.1
CF	43.8	29.2

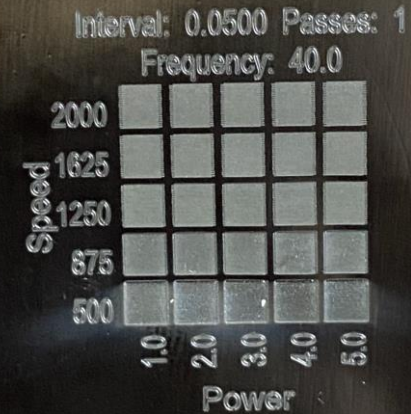
Laser Marking Film Contrast



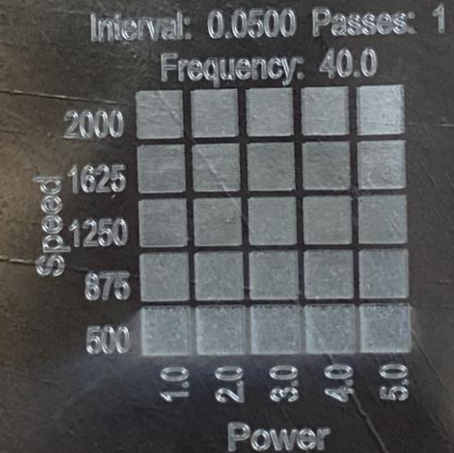
Control (PC-CF)

No LMC

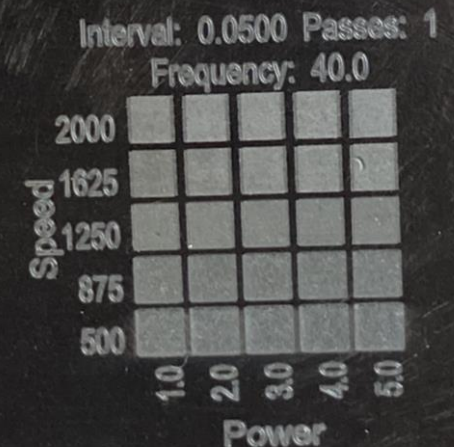
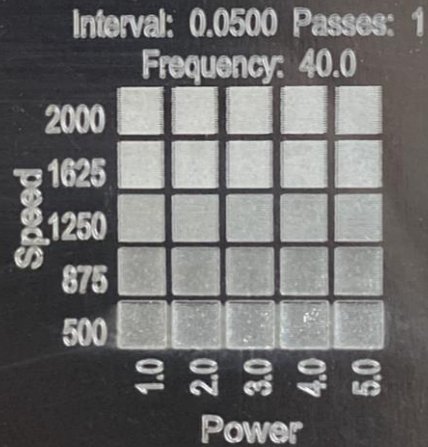
PC + dCNTs



PC + dCNTs + MCF

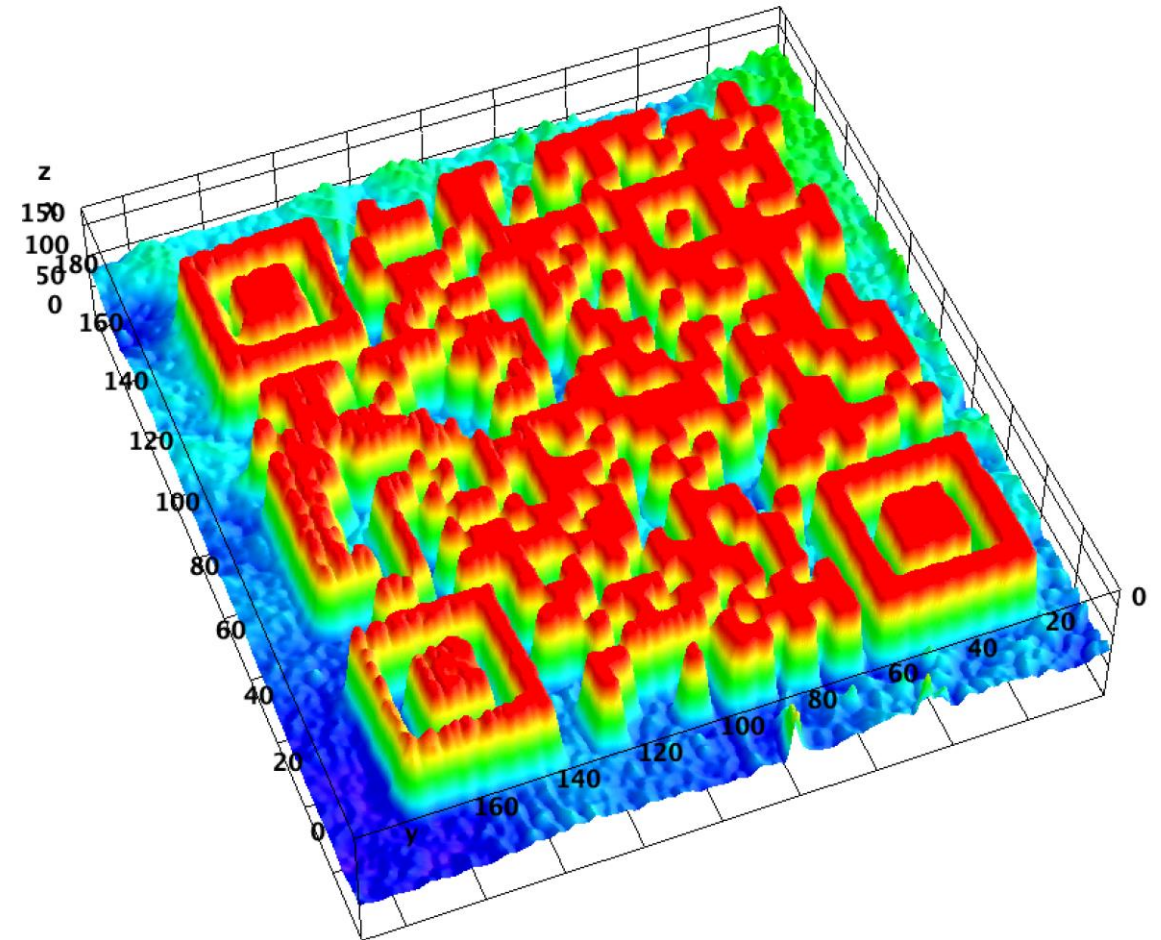


2% LMC



Laser Marking

Film Contrast



A decorative horizontal border composed of a series of white hexagons with thin black outlines, spanning the width of the slide.

THANK YOU